		JOCMA74C		0.1	
		JOCMA83C		0.05	
	Output Power Dissipation		P_O	300	mW
Total Power Dissipation			P_{tot}	375	mW
Isolation Voltage			V_{iso}	5000	Vrms
Operating Temperature			T_{opr}	-40~110	
Junction Temperature			T_j	125	
Storage Temperature			T_{stg}	-40~125	
Soldering Temperature			T_{sol}	260	

: 100μs pulse, 100Hz frequency

: AC for 1minute, R.H.=40~60%

	Turn Off Time	JOCMA39C	t_{off}	I_F=5mA, I_L=Max.	-	0.08	0.2	ms
		JOCMA38C			-	0.08	0.2	
		JOCMA57C			-	0.08	0.2	
		JOCMA66C			-	0.04	0.2	
		JOCMA75C			-	0.04	0.2	
		JOCMA74C			-	0.04	0.2	
		JOCMA83C			-	0.04	0.2	

FIG.7: Turn On Time vs. Ambient Temperature

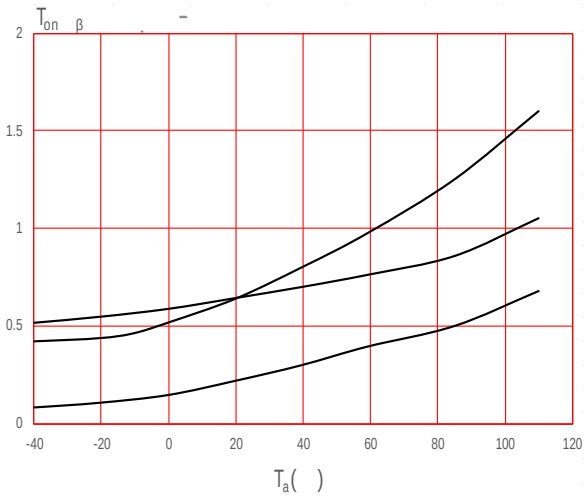
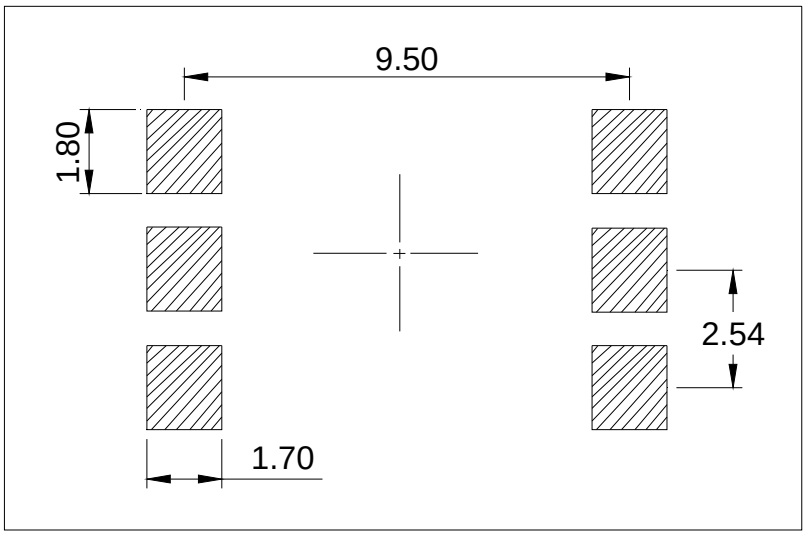
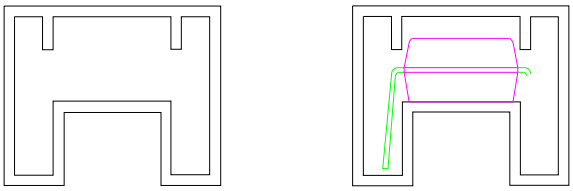


FIG.8: Turn Off Time vs. Ambient Temperature

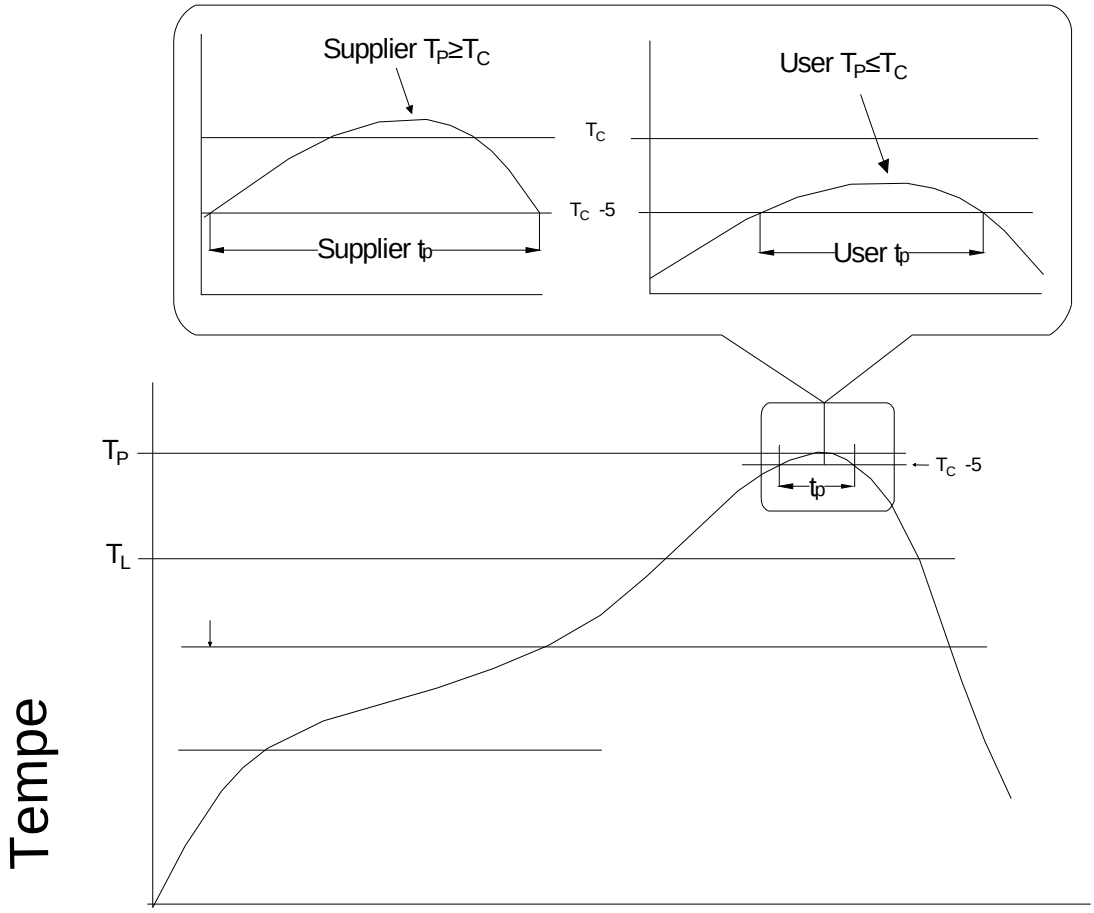
Option SMD



Standard DIP



Dimensions					
Ref.	Millimeters			Inches	
	Min.	Typ.	Max.	Min.	Typ.


Supplier $T_P \geq T_C$
User $T_P \leq T_C$
T_C
T_C -5
Supplier t_p
User t_p
T_P
T_L
T_C -5
t_p
Tempe

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.

2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.

3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.

4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.

5. The component has a shelf life of one year when stored under standard conditions.

6. Recommend storage Temp.: 0~40°C;

Recommend storage humidity: <60%;

MSL level: MSL 1